



Device Material Content

5555 NE Moore Ct.
Hillsboro OR 97124
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Package: 20 SOIC with SnPb Plating
Total Device Weight 0.53 Grams

September, 2003	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	Notes / Assumptions:
Die	1.89%	0.010			Silicon	7440-21-3	Die size: 3.15 x 2.97 mm
Mold	73.89%	0.392	5.54% 60.96% 2.22%	0.029 0.323 0.012	Mold Epoxy resin Silica Antimony Trioxide	129915-35-1 60676-86-0 1309-64-4	Mold Compound Density between 1.7 and 2.3 grams/cc 5 to 10% Epoxy resin (LSC uses 7.5% in our calculation) 75 to 90% silica filler (LSC uses 82.5% in our calculation) 1 to 5% Antimony Trioxide (LSC uses 3% in our calculation)
D/A Epoxy	0.18%	0.001			Silver-filled epoxy	7440-22-4	Die attach epoxy Density: 4 grams/cc
Wire	0.16%	0.001			Gold (Au)	7440-57-5	1.2 mil wire diameter; 1 wire for each package lead; wire length 3 mm
Lead Plating	1.26%	0.007	1.07% 0.19%	0.006 0.001	Tin (Sn) Lead (Pb)	7440-31-5 7439-92-1	Nominal: 85% Sn, 15% Pb Thickness is 0.015mm
Leadframe	22.62%	0.120	22.05%	0.117	Copper (Cu)	7440-50-8	Leadframe composition: 96 to 99% Cu (LSC uses 97.5% in our calculation) Leadframe thickness is nominal (per Case Outline).

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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